

Automotive-grade N-channel 60 V, 19 mΩ typ., 24 A STripFET™ F6 Power MOSFET in a DPAK package

Datasheet - production data

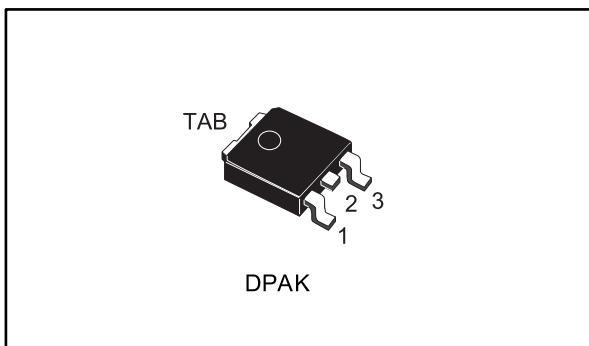
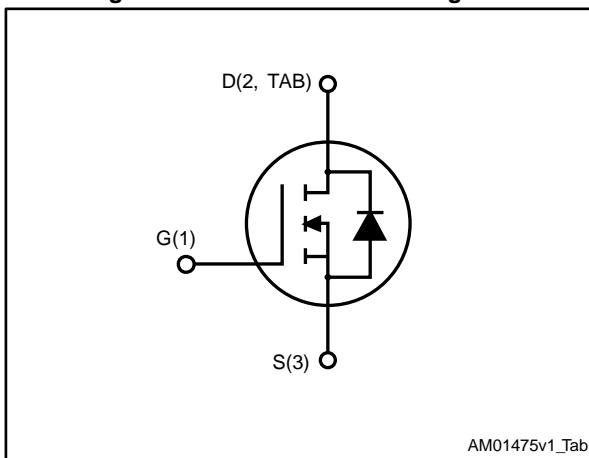


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STD30N6LF6AG	60 V	25 mΩ	24 A	40 W

- Designed for automotive applications and AEC-Q101 qualified
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the STripFET™ F6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R_{DS(on)} in all packages.

Table 1: Device summary

Order code	Marking	Package	Packing
STD30N6LF6AG	30N6LF6	DPAK	Tape and Reel

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves).....	6
3	Test circuits	8
4	Package information	9
4.1	DPAK (TO-252) type A package information.....	9
4.2	DPAK (TO-252) packing information.....	12
5	Revision history	14

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate-source voltage	± 20	V
I_D	Drain current (continuous) at $T_{case} = 25^\circ\text{C}$	24	A
	Drain current (continuous) at $T_{case} = 100^\circ\text{C}$	17	
$I_{DM}^{(1)}$	Drain current (pulsed)	96	A
P_{TOT}	Total dissipation at $T_{case} = 25^\circ\text{C}$	40	W
$E_{AS}^{(2)}$	Single pulse avalanche energy	130	mJ
T_{stg}	Storage temperature	-55 to 175	$^\circ\text{C}$
T_j	Operating junction temperature		

Notes:

(1) Pulse width is limited by safe operating area.

(2) starting $T_j = 25^\circ\text{C}$, $I_D = 24\text{ A}$, $V_{DD} = 43.5\text{ V}$.**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	3.75	$^\circ\text{C/W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	35	

Notes:(1) When mounted on a 1-inch² FR-4 board, 2 oz Cu.

2 Electrical characteristics

($T_{\text{case}} = 25^\circ\text{C}$ unless otherwise specified)

Table 4: Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 60 \text{ V}$			1	μA
		$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 60 \text{ V}$, $T_{\text{case}} = 125^\circ\text{C}$			100	
I_{GSS}	Gate-body leakage current	$V_{\text{DS}} = 0 \text{ V}$, $V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
$V_{\text{GS}(\text{th})}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	1		2.5	V
$R_{\text{DS}(\text{on})}$	Static drain-source on-resistance	$V_{\text{GS}} = 10 \text{ V}$, $I_D = 12 \text{ A}$		19	25	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5 \text{ V}$, $I_D = 12 \text{ A}$		24	30	

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{\text{DS}} = 25 \text{ V}$, $f = 1 \text{ MHz}$, $V_{\text{GS}} = 0 \text{ V}$	-	1320	-	pF
C_{oss}	Output capacitance		-	88.5	-	
C_{rss}	Reverse transfer capacitance		-	58	-	
Q_g	Total gate charge	$V_{\text{DD}} = 30 \text{ V}$, $I_D = 24 \text{ A}$, $V_{\text{GS}} = 10 \text{ V}$ (see Figure 14: "Gate charge test circuit")	-	26	-	nC
Q_{gs}	Gate-source charge		-	6	-	
Q_{gd}	Gate-drain charge		-	3.3	-	

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d}(\text{on})}$	Turn-on delay time	$V_{\text{DD}} = 30 \text{ V}$, $I_D = 12 \text{ A}$, $R_G = 4.7 \Omega$, $V_{\text{GS}} = 10 \text{ V}$ (see Figure 13: "Switching times test circuit for resistive load" and Figure 18: "Switching time waveform")	-	10	-	ns
t_r	Rise time		-	19	-	
$t_{\text{d}(\text{off})}$	Turn-off delay time		-	56	-	
t_f	Fall time		-	7	-	

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		24	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		96	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$, $I_{SD} = 24 \text{ A}$	-		1.3	V
t_{rr}	Reverse recovery time	$I_{SD} = 24 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_{DD} = 48 \text{ V}$, $T_J = 150 \text{ }^\circ\text{C}$ (see <i>Figure 15: "Test circuit for inductive load switching and diode recovery times"</i>)	-	22.4		ns
Q_{rr}	Reverse recovery charge		-	22.2		nC
I_{RRM}	Reverse recovery current		-	2		A

Notes:

(1) Current is limited by package.

(2) Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

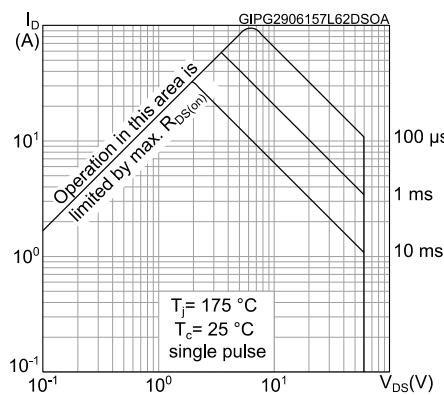
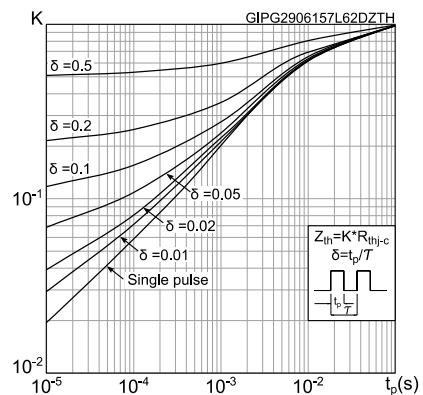
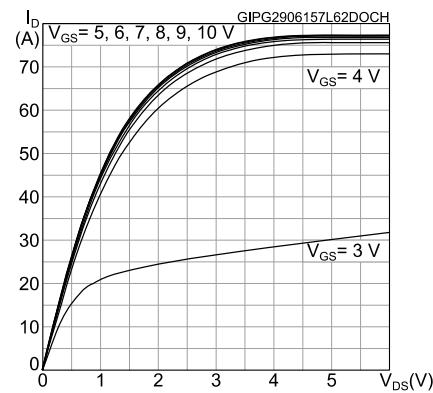
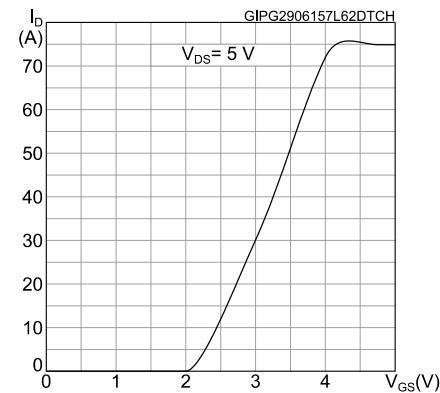
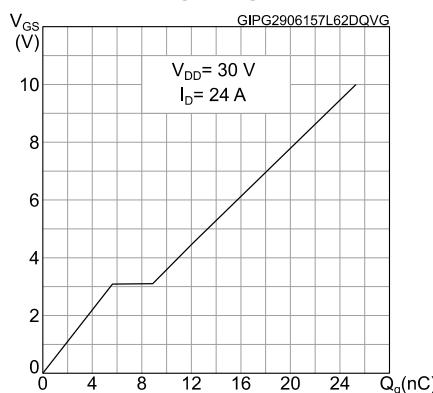
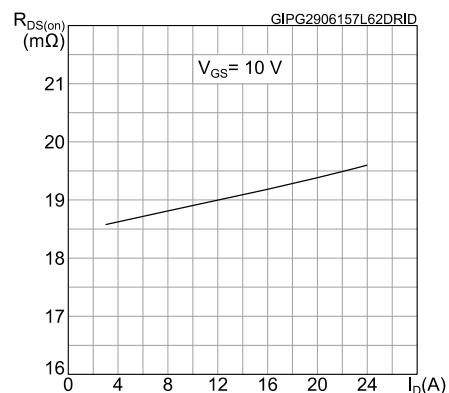
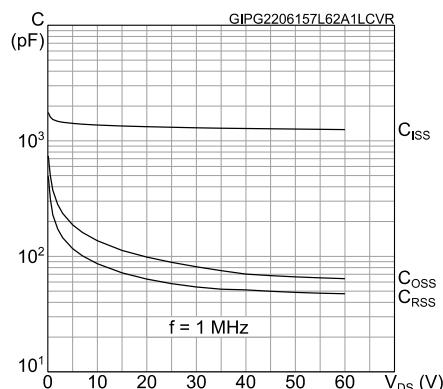
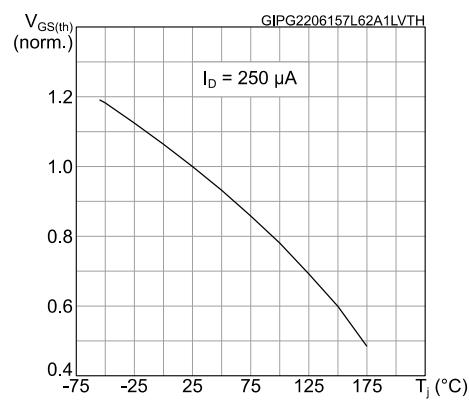
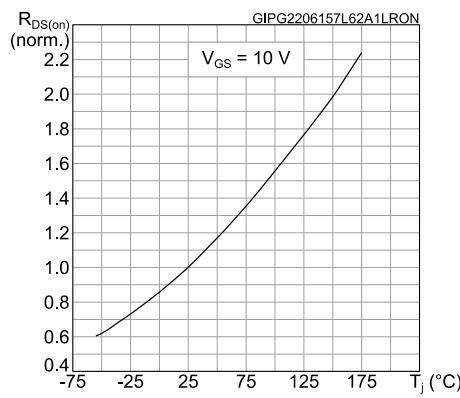
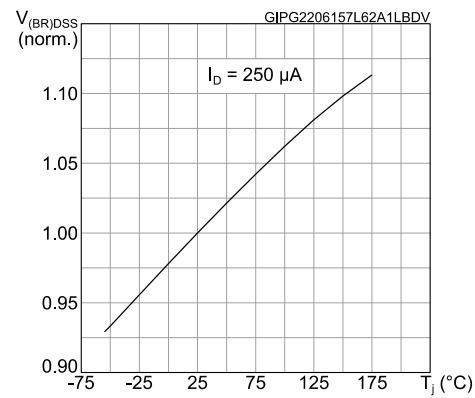
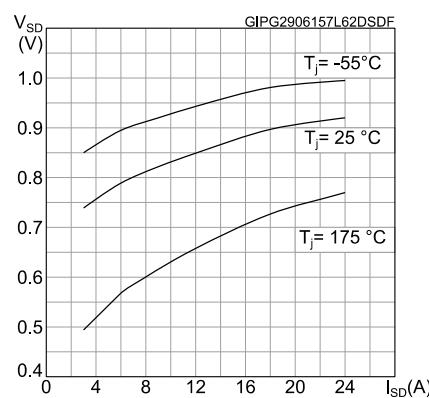
Figure 2: Safe operating area**Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

Figure 8: Capacitance variations**Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized V(BR)DSS vs temperature****Figure 12: Source-drain diode forward characteristics**

3 Test circuits

Figure 13: Switching times test circuit for resistive load

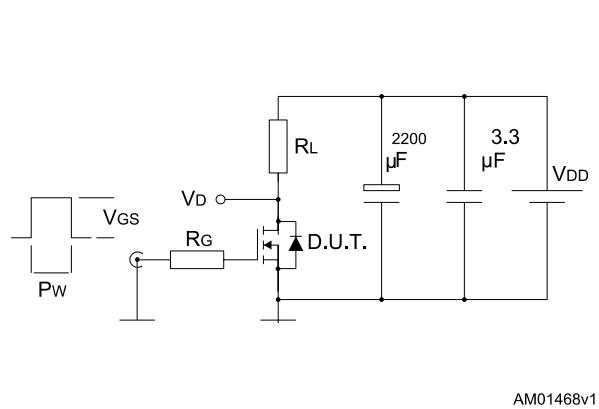


Figure 14: Gate charge test circuit

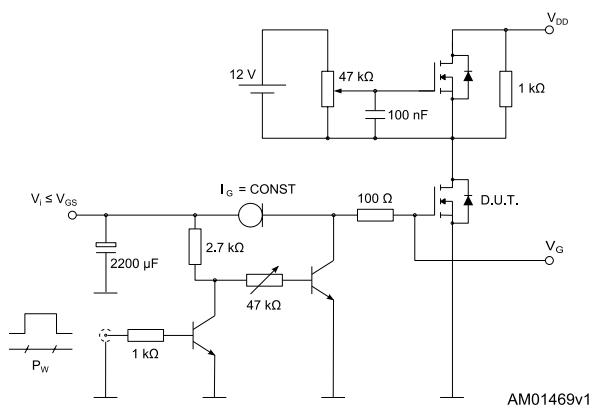


Figure 15: Test circuit for inductive load switching and diode recovery times

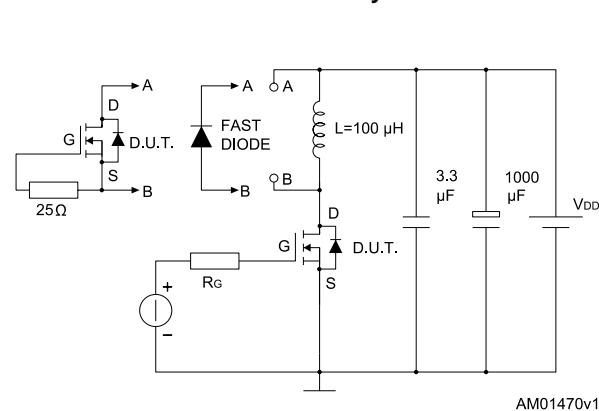


Figure 16: Unclamped inductive load test circuit

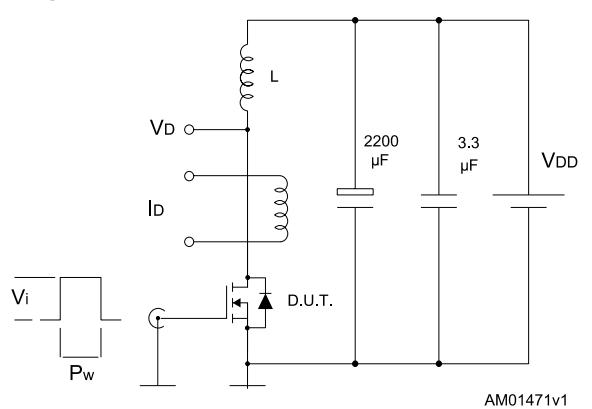


Figure 17: Unclamped inductive waveform

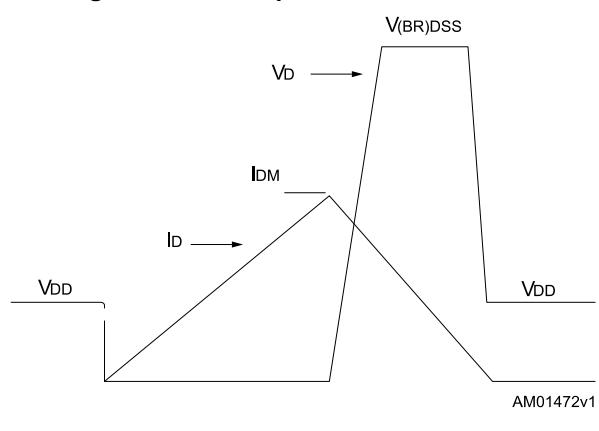
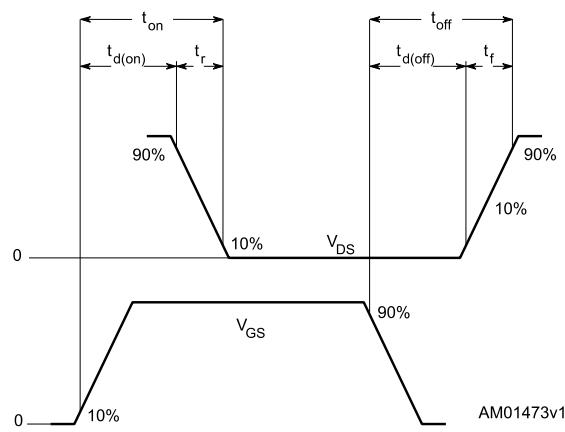


Figure 18: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A package information

Figure 19: DPAK (TO-252) type A package outline

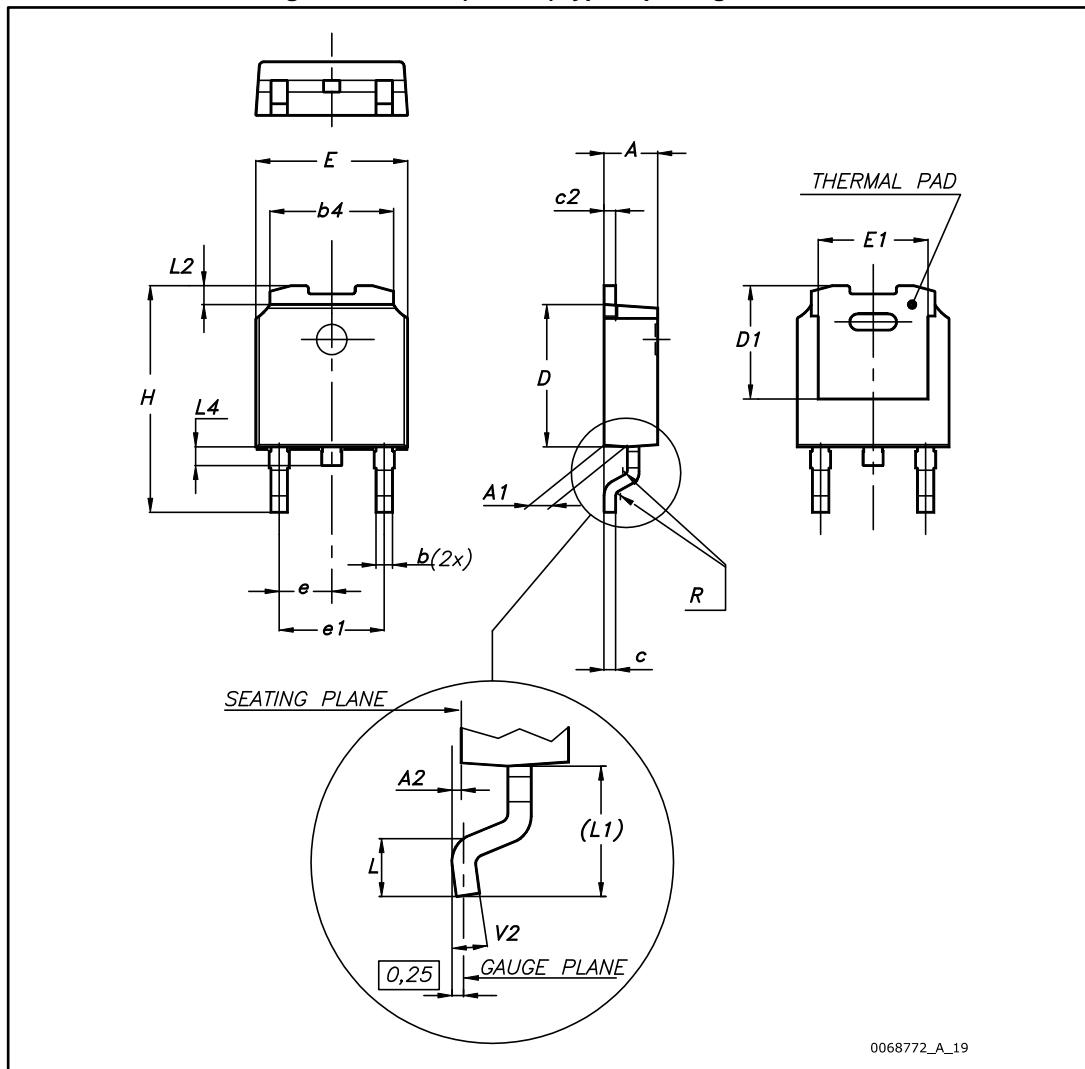
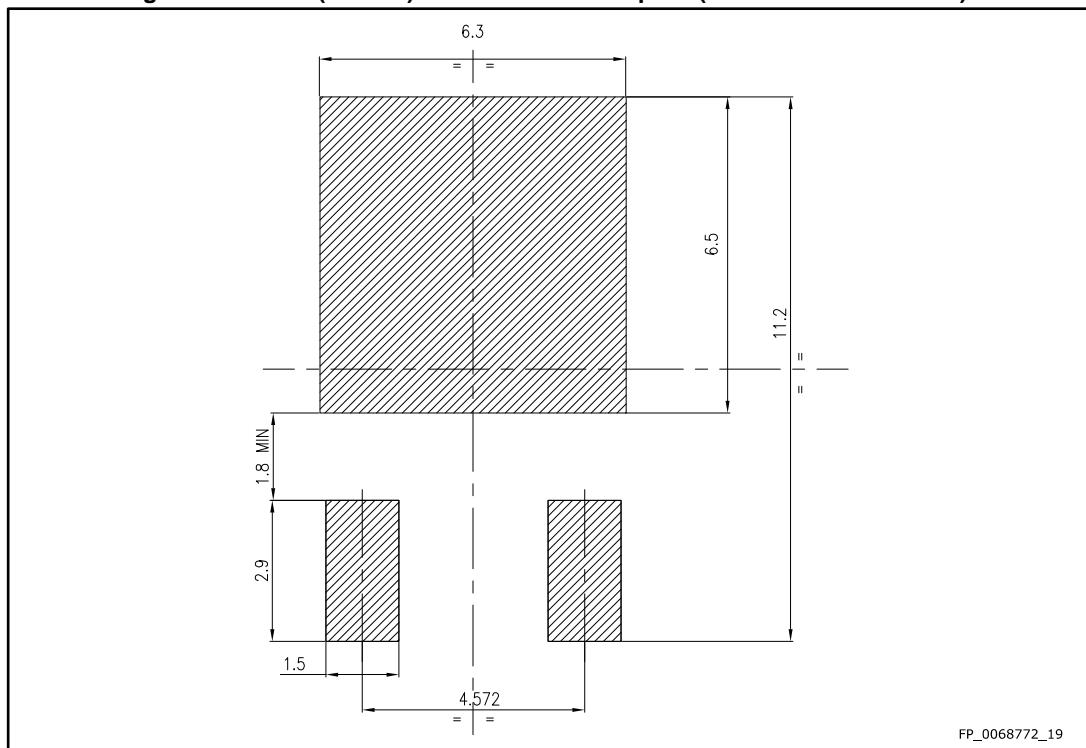


Table 8: DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 20: DPAK (TO-252) recommended footprint (dimensions are in mm)



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4.2 DPAK (TO-252) packing information

Figure 21: DPAK (TO-252) tape outline

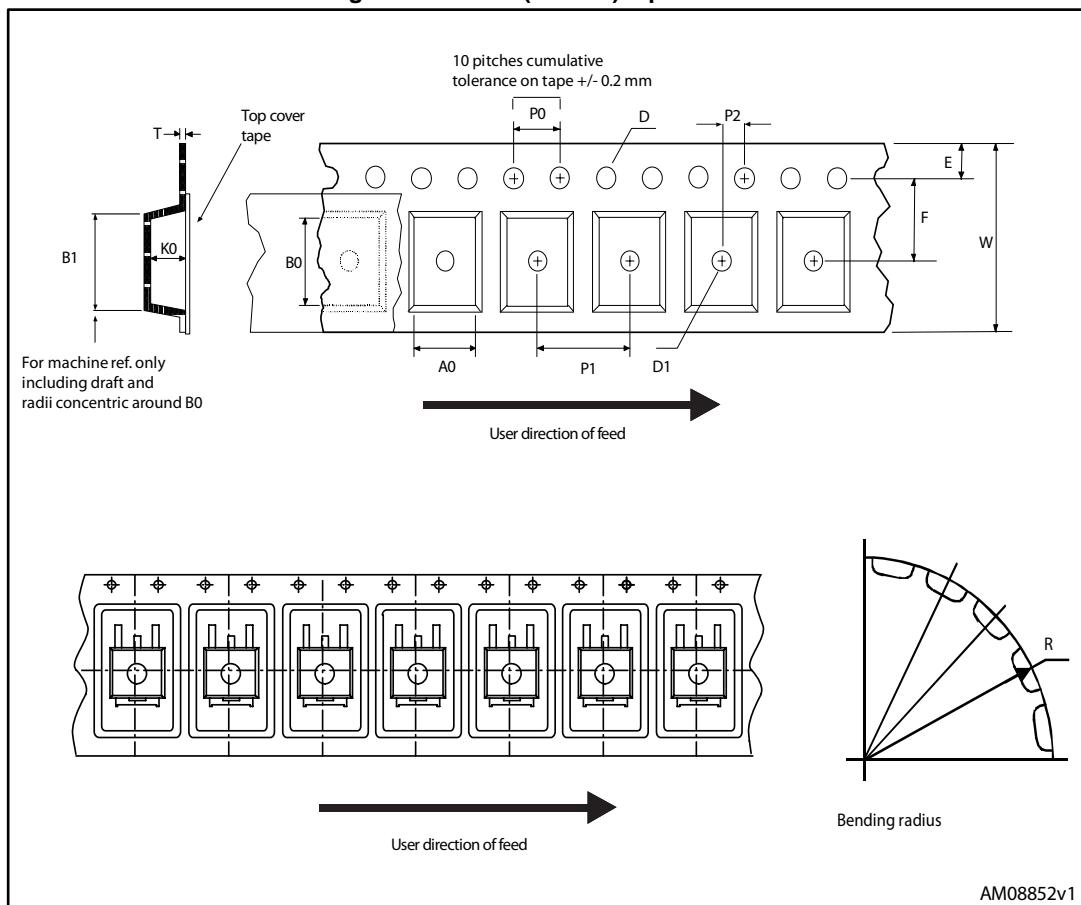


Figure 22: DPAK (TO-252) reel outline

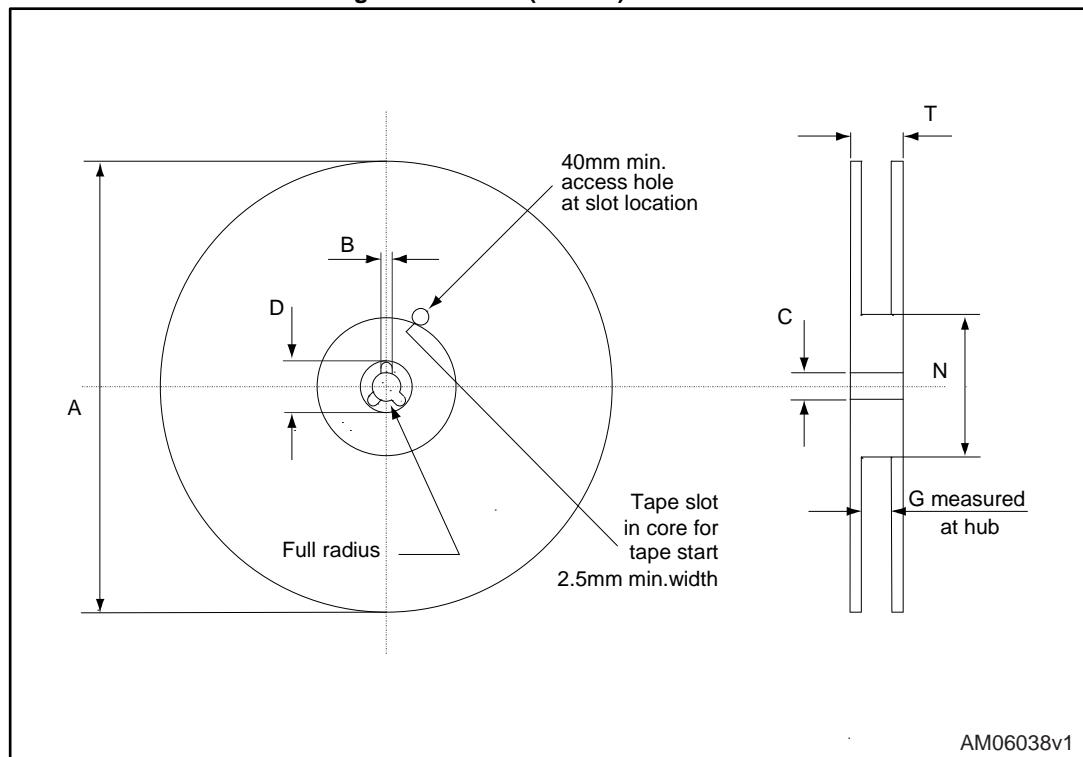


Table 9: DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
30-Jun-2015	1	First release.

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Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,
Промышленная ул, дом № 19, литер Н,
помещение 100-Н Офис 331